

Please amend the claims as follows. This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claims 1-11 (cancelled)

Claim 12 (currently amended): A method for conditioning a polishing pad, comprising:

providing a fixed abrasive polishing pad having an abrasive polishing surface, the fixed abrasive polishing pad configured to move continuously in operation in one direction between a first point and a second point, the first point being separate from the second point;

providing a web dressing media having a contact surface, the contact surface of the web dressing media being defined above the abrasive polishing surface of the fixed abrasive polishing pad;

providing a feed-roll configured to have a supply of the web dressing media;

providing a take-up roll configured to collect at least a linear portion of the web dressing media;

feeding the web dressing media from the feed-roll to the take-up roll; and

applying the contact surface of the web dressing media to the abrasive polishing surface of the fixed abrasive polishing pad prior to applying a wafer to be polished to the abrasive surface of the polishing pad while the fixed abrasive polishing pad is at least partially stabilized in position, the applying configured to dress the abrasive polishing surface of the fixed abrasive polishing pad.

Claim 13 (original): A method for conditioning a polishing pad as recited in claim 12, wherein the applying the contact surface of the web dressing media to the abrasive polishing surface of the fixed abrasive polishing pad includes:

lowering the contact surface of the web dressing media to the abrasive polishing surface of the fixed abrasive polishing pad by controllably applying pressure onto the web dressing media; and

bringing into contact the contact surface of the web dressing media to the abrasive polishing surface of the fixed abrasive polishing pad.

Claim 14 (original): A method for conditioning a polishing pad as recited in claim 12, wherein the dressing of the abrasive polishing surface of the fixed abrasive polishing pad includes:

removing polymer matrix material from pillars of the abrasive polishing surface of the fixed abrasive polishing pad, the removing being configured to expose a fresh surface of fixed abrasive materials.

Claim 15 (previously cancelled)

Claim 16 (original): A method for conditioning a polishing pad as recited in claim 12, wherein the feeding includes:

indexing the web dressing media at a programmable rate.

Claim 17 (original): A method for conditioning a polishing pad as recited in claim 12, further comprising:

dressing the abrasive polishing surface of the fixed abrasive polishing pad by moving across the abrasive polishing surface of the fixed abrasive polishing pad in a movement

direction between one of a first edge of the fixed abrasive polishing pad and a second edge of the fixed abrasive polishing pad, and a movement direction between the second edge of the fixed abrasive polishing pad and the first edge of the fixed abrasive polishing pad.

Claim 18 (original): A method for conditioning a polishing pad as recited in claim 12, further comprising:

 dressing the abrasive polishing surface of the fixed abrasive polishing pad by moving across the abrasive polishing surface of the fixed abrasive polishing pad in a movement direction between one of a center of the fixed abrasive polishing pad and an edge of the fixed abrasive polishing pad, and movement direction between the center of the fixed abrasive polishing pad and the edge of the fixed abrasive polishing pad.

Claims 19-24 (cancelled)

Claim 25 (previously amended): A polishing pad conditioner for use in a chemical mechanical polishing (CMP) apparatus, comprising:

 a fixed abrasive polishing pad having an abrasive polishing surface;

 a web dressing media having a contact surface defined between a first point and a second point, the first point being separate from the second point, wherein the web dressing media is configured to be positioned over the fixed abrasive polishing pad such that the contact surface of the web dressing media is configured to be applied to the abrasive polishing surface of the fixed abrasive polishing pad;

 a pressure application plate configured to be applied against an application surface of the web dressing media that is an opposite surface to the contact surface and is defined between a first position and a second position of the application surface of the web dressing media;

a feed-roll positioned above the fixed abrasive polishing pad media, the feed-roll being configured to have a supply of the web dressing media, the feed-roll is positioned at about the first point; and

a take-up roll positioned above the fixed abrasive polishing pad media, the take-up roll being configured to collect at least a linear portion of the web dressing media, the take-up roll is positioned at about the second point,

wherein the dressing media, the feed-roll, and the take-up roll define a web handling system, the web handling system being enclosed in a housing configured to rotate.

Claim 26 (currently amended): A polishing pad conditioner for use in a chemical mechanical polishing (CMP) apparatus, comprising:

a fixed abrasive polishing pad having an abrasive polishing surface;

a web dressing media having a contact surface defined between a first point and a second point, the first point being separate from the second point, wherein the web dressing media is configured to be positioned over the fixed abrasive polishing pad such that the contact surface of the web dressing media configured to be applied to the abrasive polishing surface of the fixed abrasive polishing pad; and

a pressure application plate configured to be applied against an application surface of the web dressing media that is an opposite surface to the contact surface and is defined between a first position and a second position;

wherein the web dressing media and the pressure application plate are enclosed in a housing configured to rotate.

Claim 27 (cancelled)

Claim 28 (new): A substrate polishing system, comprising:

a first roller;

a second roller, the first and second roller being aligned along a horizontal plane;

a pad belt configured to be wrapped around the first roller and second roller, the pad belt having a first horizontal plane defining a top of the pad belt and a second horizontal plane defining a bottom of the pad belt, the horizontal plane of the first and second rollers being parallel to the first and second horizontal planes, the top of the pad belt defining a substrate application region; and

an application device for applying a web dressing media to a surface of the pad belt, the application device being applied on one of the top and the bottom of the pad belt.

Claim 29 (new): A system as recited in claim 28, the substrate polishing system further comprising:

a feed-roll being defined on a same side as the application device, the feed-roll configured to have a supply of the web dressing media, the feed-roll being positioned at about a first point; and

a take-up roll being defined on the same side as the application device, the take-up roll configured to collect at least a linear portion of the web dressing media, the take-up roll being positioned at about a second point.

Claim 30 (new): A system as recited in claim 29, wherein the feed-roll, the take-up roll, and the web dressing media define a web handling system.

Claim 31 (new): A system as recited in claim 28, further comprising:

a stabilization member for controllably applying the application device to the web dressing media so as to apply the web dressing media to the surface of the pad belt.

Claim 32 (new): A system as recited in claim 31, wherein the stabilization member includes an application arm.

Claim 33 (new): A system as recited in claim 28, wherein the application device can be one of a plate, a disk, and a roller.

Claim 34 (new): A system as recited in claim 28, where in the polishing pad is a fixed abrasive polishing pad.

Claim 35 (new): A system as recited in claim 34, wherein applying the web dressing media to the surface of the pad belt is configured to remove an amount of polymer matrix material an abrasive surface of the pad belt, thereby exposing a fresh surface of fixed abrasive material.

Claim 36 (new): A system for polishing a wafer, comprising:

a polishing disk having a top surface and a bottom surface, the top surface defining a wafer application region; and

a pressure application member being defined above the top surface of the polishing disk, the pressure application member configured to apply a web dressing media to the top surface of the polishing disk.

Claim 37 (new): A system as recited in claim 36, further comprising:

a feed-roll being defined above the top surface of the polishing disk, the feed-roll configured to have a supply of the web dressing media, the feed-roll being positioned at about a first point; and

a take-up roll being defined above the top surface of the polishing disk, the take-up roll configured to collect at least a linear portion of the web dressing media, the take-up roll being positioned at about a second point.

Claim 38 (new): A system as recited in claim 27, wherein the feed-roll, the take-up roll, and the web dressing media define a web handling system.

Claim 39 (new): A system as recited in claim 37, further comprising:

a stabilization member for controllably applying the pressure application member to the web dressing media so as to apply the web dressing media to the to the top surface of the polishing disk.

Claim 40 (new): A system as recited in claim 39, wherein the stabilization member includes an application arm.

Claim 41 (new): A system as recited in claim 28, wherein the pressure application member can be one of a plate, a disk, and a roller.